MACOM GaN is Transforming the Network

- Smaller PCBs
- Lower heat sink cost
- Single GaN device replacing multiple LDMOS devices
- High efficiency
- Multi-band
- Smaller, lighter equipment  
  ➔ Reduced tower load
- Integration
- High efficiency
- High power density
- Single radio for 1.8 GHz and 2.2 GHz
- Enables 3.5 GHz to 6 GHz
- Simpler devices leading to shorter development time
- Broadband ➔ fewer PAs to deal with when covering all bands
- Excellent applications support
- Higher power density
  ➔ Smaller package
- Higher efficiency
  ➔ Smaller heat sink
- Broadband ➔ Enables carrier aggregation
- High frequency ➔ Supports 3.5 GHz to 6 GHz